

**Notice of References Cited**

Application/Control No.

10/767,658

Applicant(s)/Patent Under  
Reexamination  
OKAMOTO ET AL.

Examiner

Shambhavi Patel

Art Unit

2128

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Sarval et al. 'Effective Modeling of the Reflow Soldering Process: Bases, Construction, and Operation of a Process Model'. IEEE Transactions on Component, Packaging, and Manufacturing Technology--Part C, Vol. 21, No. 2. April, 1998.
	V	
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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